	Hits	Search Text	DBs
10	2	430/311.ccls. and ((semiconductor or wafer or substrate) near9 (die or circuit$5 or (integrated near9 circuit$4) or (imag$4 near9 circuit$5)) near12 (cover or lid or plate or template or encapsula$5) near13 ((transparent near9 region) or $6lithograph$6 or pattern$4 or photolithograph$6 or aperture)) and (encapsulat$4 near9 packag$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
11	7	257/434.ccls. and ((semiconductor or wafer or substrate or wafer or sensor or device) near14 (die or circuit$5 or (integrated near9 circuit$4) or (imag$4 near9 circuit$5)) near14 (cover or lid or plate or template or encapsula$5) near13 ((transparent near9 region) or $6lithograph$6 or pattern$4 or photolithograph$6 or aperture)) and ((encapsulat$4 near9 packag$4) or housing or packag$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB

	Hits	Search Text	DBs
12	7	257/433.ccls. and (((semiconductor or wafer or substrate or wafer or sensor or device) near14 (die or circuit$5 or (integrated near9 circuit$4) or (imag$4 near9 circuit$5))) same ((cover or lid or plate or template or encapsula$5) near13 ((transparent near9 region) or $6lithograph$6 or pattern$4 or photolithograph$6 or aperture)) same (photosensitive or light$4sensitive or epoxy or photo$4cur$4 or resist or photoresist)) and ((encapsulat$4 near9 packag$4) or housing or packag$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
13	3	257/435.ccls. and (((semiconductor or wafer or substrate or wafer or sensor or device) near14 (die or circuit$5 or (integrated near9 circuit$4) or (imag$4 near9 circuit$5))) same ((cover or lid or plate or template or encapsula$5) near13 ((transparent near9 region) or $6lithograph$6 or pattern$4 or photolithograph$6 or aperture))) and ((encapsulat$4 near9 packag$4) or housing or packag$4) and (photosensitive or photocur$4 or cur$4 or epoxy or resist or photoresist)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB

	Hits	Search Text	DBs
14	12	257/434.ccls. and ((semiconductor or wafer or substrate or wafer or sensor or device) near14 (die or circuit$5 or (integrated near9 circuit$4) or (imag$4 near9 circuit$5) or image)) and (((cover or lid or plate or template or encapsula$5) near13 (shield or (transparent near9 region) or $6lithograph$6 or pattern$4 or photolithograph$6 or aperture or screen$4 or silk$4screen$4))) and ((encapsulat$4 near9 packag$4) or housing or packag$4) and ((spacing or support) same (structure or region or area))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
15	15	250/239.ccls. and (((semiconductor or wafer or substrate or wafer or sensor or device) near14 (die or circuit$5 or (integrated near9 circuit$4) or (imag$4 near9 circuit$5) or image)) same ((cover or lid or plate or template or encapsula$5) near13 (shield or (transparent near9 region) or $6lithograph$6 or pattern$4 or photolithograph$6 or aperture))) and ((encapsulat$4 near9 packag$4) or housing or packag$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB

	Hits	Search Text	DBs
16	1	250/239.ccls. and (((semiconductor or wafer or substrate or wafer or sensor or device) near14 (die or circuit$5 or (integrated near9 circuit$4) or (imag$4 near9 circuit$5))) same ((cover or lid or plate or template or encapsula$5) near13 ((transparent near9 region) or $6lithograph$6 or pattern$4 or photolithograph$6 or aperture))) and ((encapsulat$4 near9 packag$4) or housing or packag$4) and (photosensitive or photocur$4 or cur$4 or epoxy or resist or photoresist) and ((support or spacing) near9 (structure or region))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
17	3	250/208.1.ccls. and (((semiconductor or wafer or substrate or wafer or sensor or device) near14 (die or circuit$5 or (integrated near9 circuit$4) or (imag$4 near9 circuit$5))) same ((cover or lid or plate or template or encapsula$5) near13 ((transparent near9 region) or $6lithograph$6 or pattern$4 or photolithograph$6 or aperture))) and ((encapsulat$4 near9 packag$4) or housing or packag$4) and (photosensitive or photocur$4 or cur$4 or epoxy or resist or photoresist)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB

	Hits	Search Text	DBs
18	79	250/239.ccls. and ((semiconductor or wafer or substrate or wafer or sensor or device) near14 (die or circuit$5 or (integrated near9 circuit$4) or (imag$4 near9 circuit$5) or image)) and (((cover or lid or plate or template or encapsula$5) near13 (shield or (transparent near9 region) or $6lithograph$6 or pattern$4 or photolithograph$6 or aperture or screen$4 or silk$4screen$4))) and ((encapsulat$4 near9 packag$4) or housing or packag$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB